ATTACHMENT B
Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A cooling assembly for at least one board, the at least one board having mounted thereon a plurality of components including a first component and a further component, the cooling assembly comprising:

a first passage;

a first fan for passing air through the passage;

an isolation assembly for generally enclosing heat generated from the first component, the first component mounted on the at least one board being enclosed within the isolation assembly, the isolation assembly containing at least a part of the first passage, and the isolation assembly being removably attachable to a computer case without opening the computer case;

a further passage configured to provide air flow past the further component mounted on the at least one board outside of the isolation assembly; and

a second fan for passing air through the further passage~~.~~,

said first component comprising a processor having a passive heat sink operably coupled thereto.

2. (Canceled)

3. (Previously Presented) The cooling assembly of claim 1, wherein the first passage includes a conduit, separate from the first and second fans, in communication with the isolation assembly.

4. (Canceled)

5. (Original) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

6. (Original) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

7.-32. (Canceled)

33. (Previously Presented) The cooling assembly of claim 1, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

34. (Currently Amended) A cooling assembly for at least one board, the at least one board having mounted thereon a plurality of components including a first component and a further component, the cooling assembly comprising:

a first passage;

a first fan for passing air through the passage;

an isolation assembly for generally enclosing heat generated from the first component, the first component mounted on the at least one board being enclosed within the isolation assembly, and the isolation assembly containing at least a part of the first passage;

a further passage configured to provide air flow past the further component mounted on the at least one board outside of the isolation assembly; and

a second fan for passing air through the further passage~~.~~

said first component comprising a processor having a passive heat sink operably coupled thereto.

35. (Canceled)

36. (Previously Presented) The cooling assembly of claim 34, wherein the alternate passage includes a conduit in communication with the isolation assembly.

37. (Canceled)

38. (Previously Presented) The cooling assembly of claim 34, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

39.-40. (Canceled)

41. (Previously Presented) The cooling assembly of claim 34, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

42.-43. (Canceled)

44. (Previously Presented) The cooling assembly of claim 1, further comprising:

an exhaust hole in communication with the first passage and suitable for venting air through the computer case.

45. (Previously Presented) The cooling assembly of claim 44, wherein an air path from the first fan through the exhaust hole passes through the first passage.

46. (Previously Presented) The cooling assembly of claim 44, wherein the cooling assembly is configured such that at least 80% of the air passing through the first fan is vented through the exhaust hole.

47. (Previously Presented) The cooling assembly of claim 44, wherein the cooling assembly is configured such that substantially all of the air passing through the first fan is vented through the exhaust hole.

48. (Previously Presented) The cooling assembly of claim 34, further comprising:

an exhaust hole in communication with the first passage and suitable for venting air through the computer case.

49. (Previously Presented) The cooling assembly of claim 48, wherein an air path from the first fan through the exhaust hole passes through the first passage.

50. (Previously Presented) The cooling assembly of claim 48, wherein the cooling assembly is configured such that at least 80% of the air passing through the first fan is vented through the exhaust hole.

51. (Previously Presented) The cooling assembly of claim 48, wherein the cooling assembly is configured such that substantially all of the air passing through the first fan is vented through the exhaust hole.